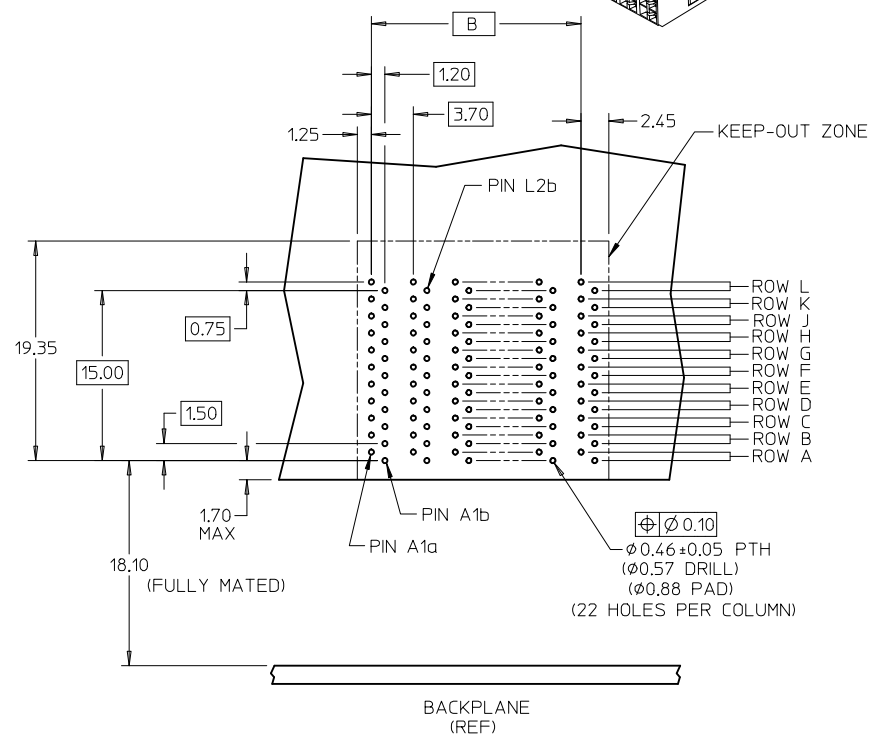
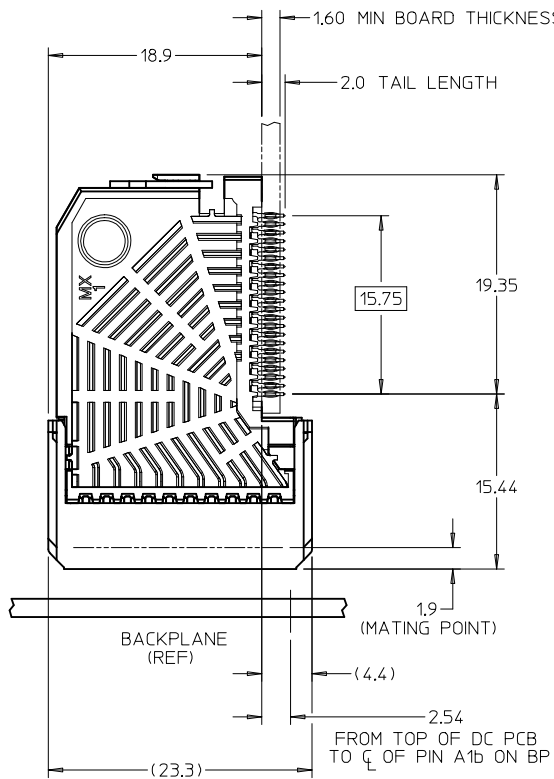
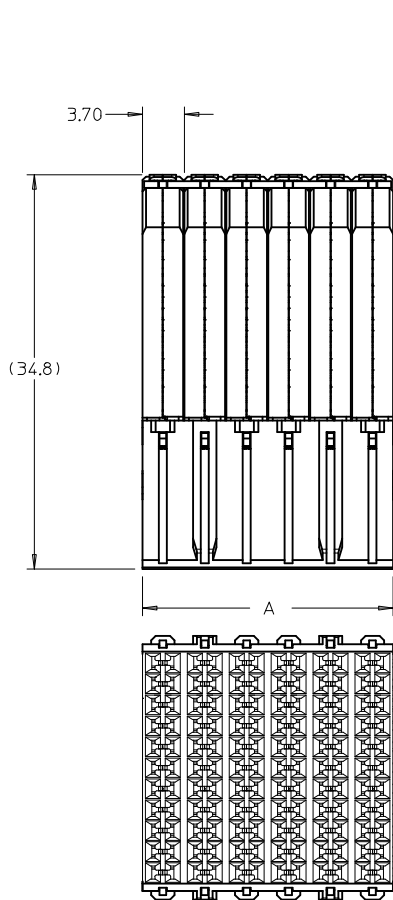
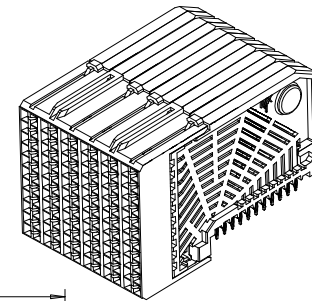


MATERIAL NUMBER	# OF COLUMNS	DIM "A" MAX	DIM "B"
75710-***5	5	18.50	14.80
75710-***6	6	22.20	18.50
75710-***8	8	29.60	25.90
75710-***0	10	37.00	33.30

75710-***0**

MODULE TYPE -- TAIL PLATING TYPE
 UNGUIDED -- MATTE TIN (FORMERLY TIN/LEAD) = 0
 UNGUIDED -- MATTE TIN = 1

OF COLUMNS/PLATING
 05 = 5 COL 30 GOLD
 06 = 6 COL 30 GOLD
 08 = 8 COL 30 GOLD
 10 = 10 COL 30 GOLD
 55 = 5 COL 10 GOLD (MAPS)
 56 = 6 COL 10 GOLD (MAPS)
 58 = 8 COL 10 GOLD (MAPS)
 50 = 10 COL 10 GOLD (MAPS)



DAUGHTERCARD HOLE PATTERN
(CONNECTOR SIDE)

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP) GLASS-FILLED, UL94V-0
TERMINALS - HIGH PERFORMANCE COPPER ALLOY
2. FINISH: SELECTIVE GOLD IN CONTACT AREA.
SELECTIVE MATTE TIN ON PCB TAILS, NICKEL OVERALL.
3. REFER TO MOLEX PRODUCT SPEC PS-75710-999 FOR PERFORMANCE SPECIFICATIONS.
4. PRODUCT IS PACKAGED PER PK-70873-609.
5. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
6. MAPS (MOLEX ADVANCED PLATING SYSTEM)

REV	DESCRIPTION	QUALITY SYMBOLS
1	LEAD FREE CON/ MAPS	$\nabla = 0$
2	EC NO: UCP2013-4121	$\nabla = 0$
3	IDRW:RHP/PPLE 2013/04/01	$\nabla = 0$
4	CHKD:MMOLFE 2013/04/01	$\nabla = 0$
5	APPR:SMILLER 2013/07/15	$\nabla = 0$

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.13	± ---
1 PLACE ± 0.25	± ---
0 PLACE ±	±
ANGULAR ±1/2°	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
JLAURX	09/01/2005
CHECKED BY	DATE
NMARTIN	09/01/2005
APPROVED BY	DATE
CBIXLER	09/01/2005
MATERIAL NO.	
SEE CHART	
SIZE	
C	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
3:1	METRIC	
I-TRAC DAUGHTERCARD 11 ROW SIGNAL MODULE UNGUIDED SALES DWG		
molex		
DOCUMENT NO.		SHEET NO.
SD-75710-001		1 OF 1
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